



PIP2 MEBT Kicker Review

Greg Saewert

Chopper Review Meeting

2 August 2018

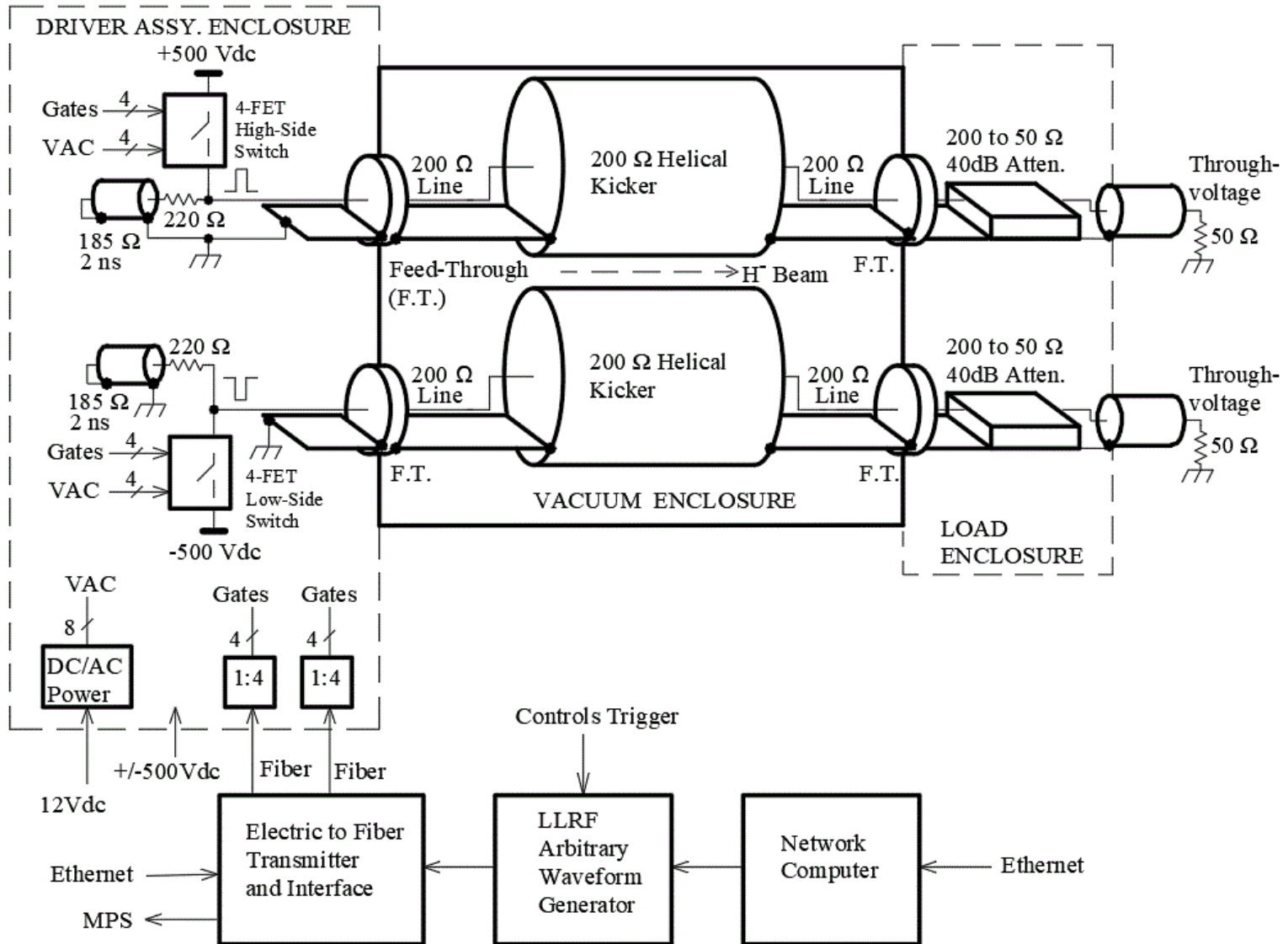
Outline

- Requirements overview & system design approach
- Challenges
- Design details
- Electrical performance results
- Issues to be addressed

Kicker Requirements

- Kick individual bunches (bunch-by-bunch)
- Rise/fall time 4.0 ns (5-95%) maximum between bunches
 - This leaves 2.15 ns flattop to both kick and pass
- Kicking scheme
 - +/- 500 V to kick beam out, 0 V to pass
- Kick an arbitrary pattern for Booster delivery (at 20 Hz)
 - 45 MHz average switching rate during 550 μ s macro-pulse
 - 0.5 MHz overall average switching rate
- Beam test modes
 - 81.25 MHz switching rate for 10's of μ s, at 20 Hz
 - Any arbitrary pattern having switching rates <81 MHz and <0.5 MHz average

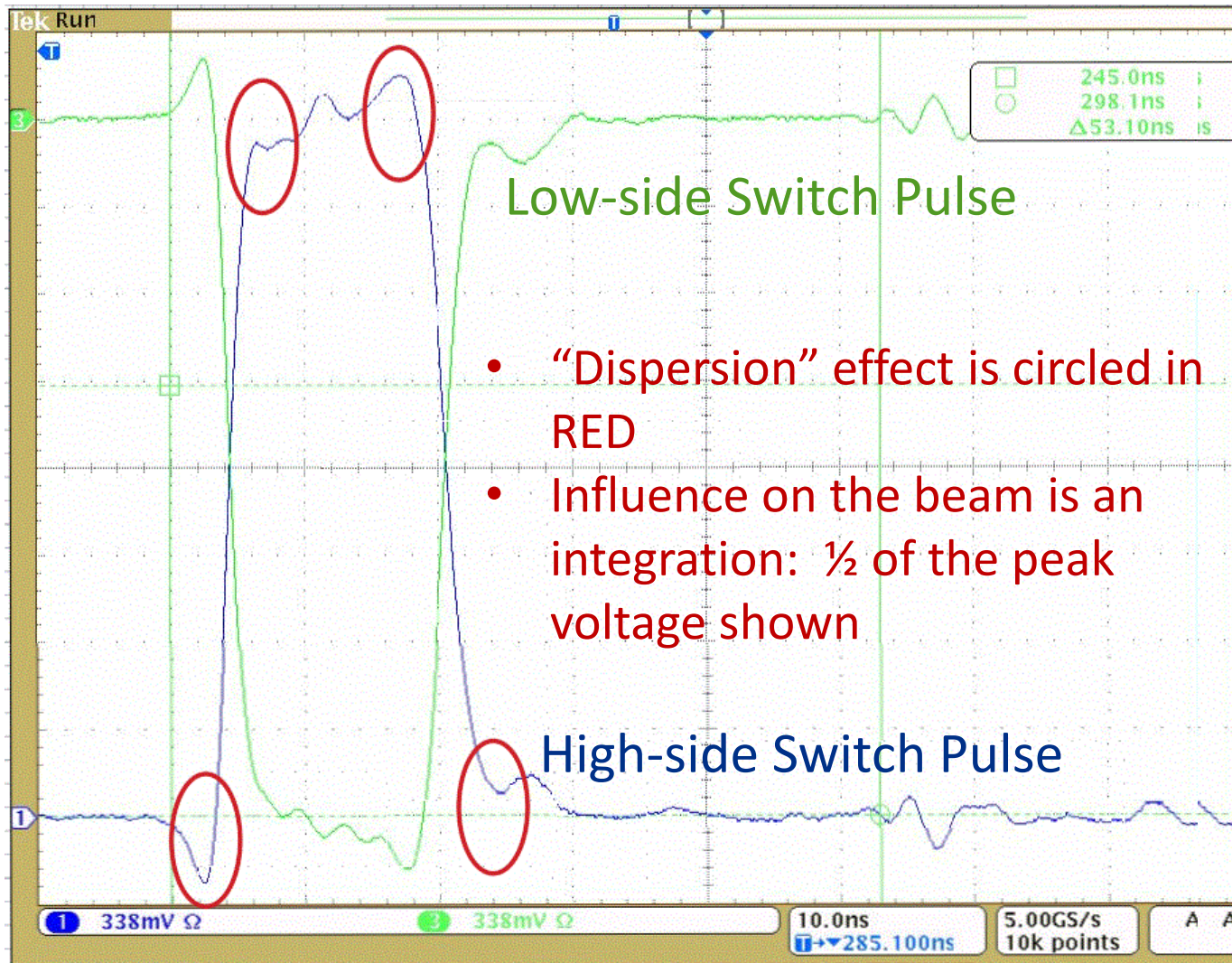
Kicker System



Overview – the Helix

- Dual 200 Ohm helical, traveling wave structure
 - 200 Ω (as opposed to typical 50) lowers drive current and power making fast switching conceivable
 - $\ll 10$ Watts RF skin effect losses in the vacuum
 - Symmetric and broadband structure
 - Potentially low internal reflections
- Thermal design
 - ~ 0.1 gpm water-cooled ground tube for 40 W beam loss
- Includes protection electrodes
- Challenges
 - Match propagation to beam velocity
 - Reflections
 - Discontinuities between helix, 200 Ω strip lines and load
 - Frequency dependent effect (referred to as “dispersion”)
 - Cause: inter-winding coupling and winding capacitance to ground

“Dispersion” Effect



Addressing the Helix Design Challenges

- Propagation time is matched to beam beta by a tuning procedure
 - Both prototype helices were tuned to -0.5% of ideal
- Reflection issues
 - Microstrip lines in and out are designed for 200 Ohms
 - Feed-through to strip line to helix reflections are low
 - Helix low impedance end-effects cause reflections
 - Coupling between windings raises strip line impedance from ~140 to 200 Ω ... but the turn at each end lacks the coupling
 - Modeling used to find suitable compensation scheme
 - Ground tube stepped 1-turn, both ends, raises impedance
 - Reflection reduced about 30%
 - Load reflection can be compensated with small series inductance
 - Switch-driver close to feed-through (and no coax) reduces reflections
- Dispersion effect reduction
 - Helices are located away from ground surfaces by 1.75"
 - Helix dimensions were chosen to be slightly faster than beam beta
 - Adding inter-winding capacitive plates provides compensation
 - Compensation decreases dispersion and increases propagation time
 - Integrated value of dispersion voltage peaking reduced to <5%

Overview – Helix Drivers

- Kicker drivers are fast switches
 - One single-switch driver per helix, opposite voltage polarity
- Apply ± 500 V to kick beam out, 0 V to pass
- Switches are series-connected FETs to share switching losses
 - Total switch switching loss from Cds, 3 FETs in series:

$$3 * \frac{1}{2} Cds \left(\frac{v}{3}\right)^2 f = \frac{1}{3} * \frac{1}{2} Cds V^2 f \quad (Watts)$$

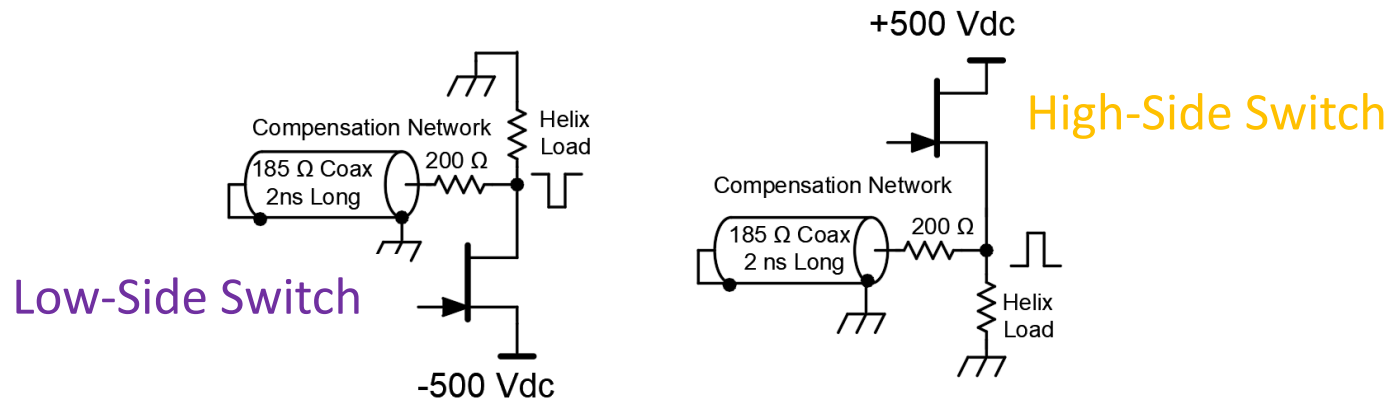
- Switch construction
 - Each switch fully isolated
 - Each FET is individually gated simultaneously
- Driver design challenges
 - Switch on and off fast enough
 - Custom FET gate driver required for this switching speed
 - Determine FETs reliability to handle thermal cycling
 - Handling switching losses for Booster requirement
 - 1 μ J switching loss per cycle – capacitive switching loss
 - 45 Watts are dissipated per FET at 45 MHz rep rate

Addressing the Driver Design Challenges

- Photonics laser and transmitter provides precision triggering
 - The generator signal gates laser
 - Splitters deliver triggering to all FETs simultaneously to photo detectors on each GaNFET driver board
- Switching speed is obtained using GaN FETs (GaN Systems, Inc.)
 - GS66502B: 7 Adc, 15 A pulsed; 650 V; 20 pF d-s, 65 pF g-s
 - GaNFET driver circuit kept as small as conveniently possible minimizing parasitics
- Custom FET gate driver circuit designed with operating margin
 - Turn-on time is settable to <2 ns
 - 3-FET switches operate at 500 V above 90 MHz; and 81.25 MHz at 600 V
 - A Calibration procedure used to match FET timing
 - Both turn-on and -off delay are matched to +/-100 ps
 - Allowance remains for shifts due to time and temperature

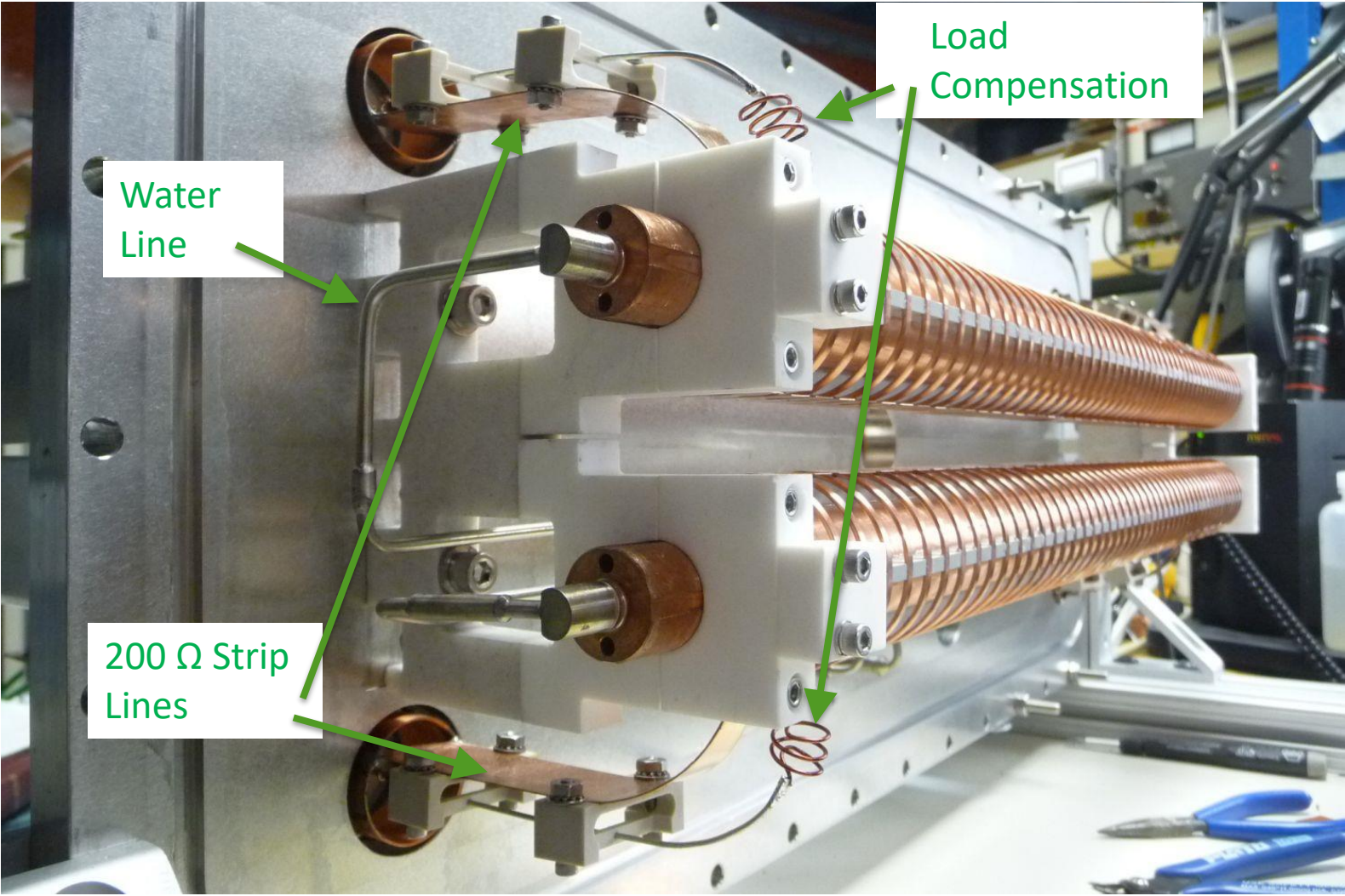
Addressing the Driver Design Challenges (cont.)

- FET reliability test: 3-FET switch was operated for 4 months 24/7
 - 500 V bias, 45 MHz for 550 μ s at 20 Hz (Booster ave. switching rates)
 - No evident timing variations
 - Demonstrates GaN FETs are not overly stressed
- Turn-off time reduced to <4 ns with compensation:



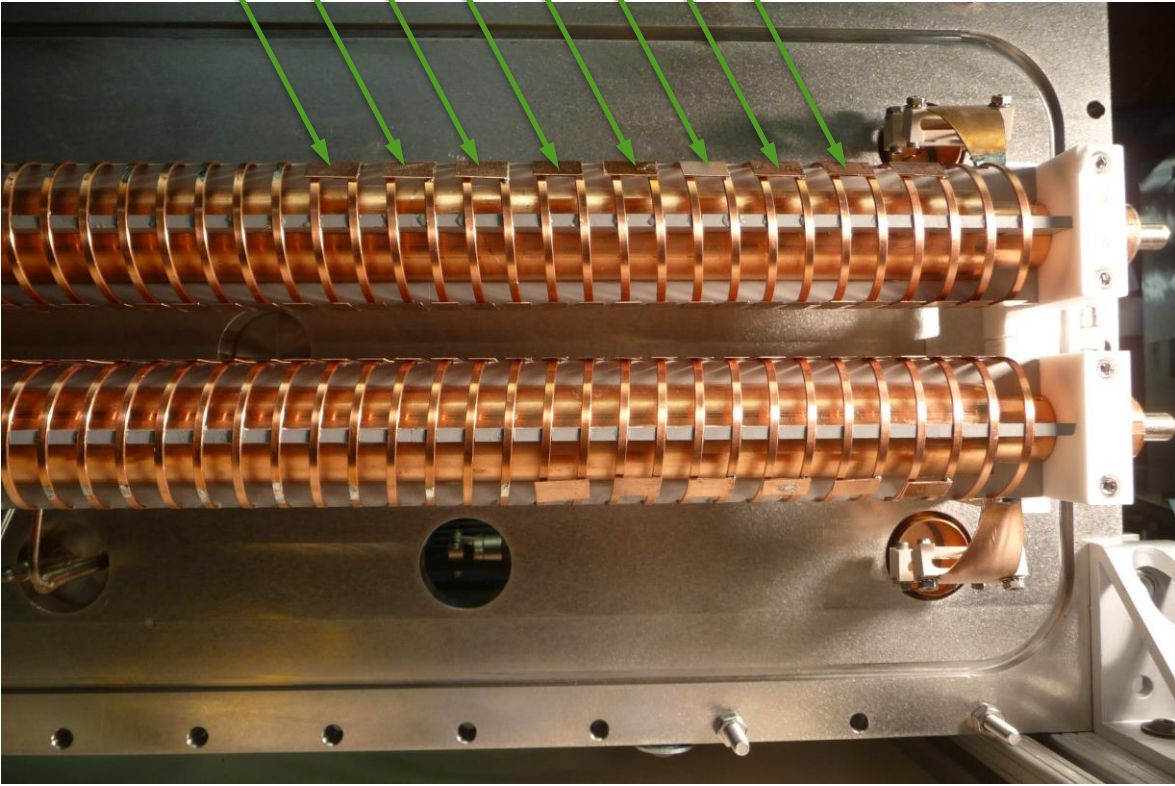
- 500 V on the plate assumes 100% efficient kicker
 - Helices are 95-97% efficient
 - 3 V drop in the switch
 - Required bias voltage is ~528 Vdc
 - **Our present limit is 500 Vdc bias voltage**

Helical kickers

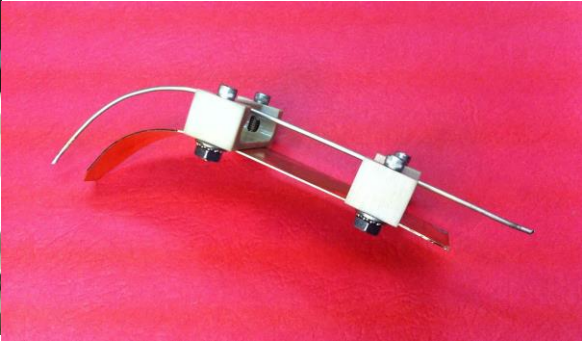
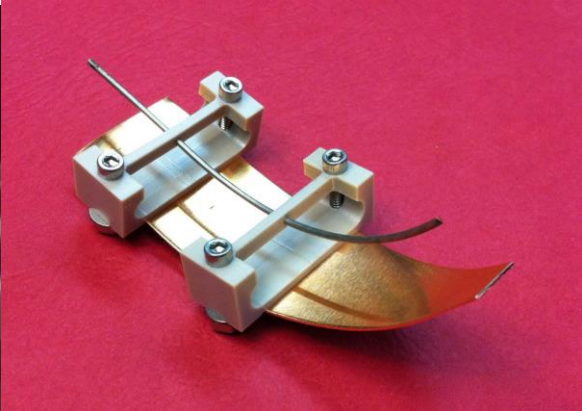


Dual-Helix Assembly

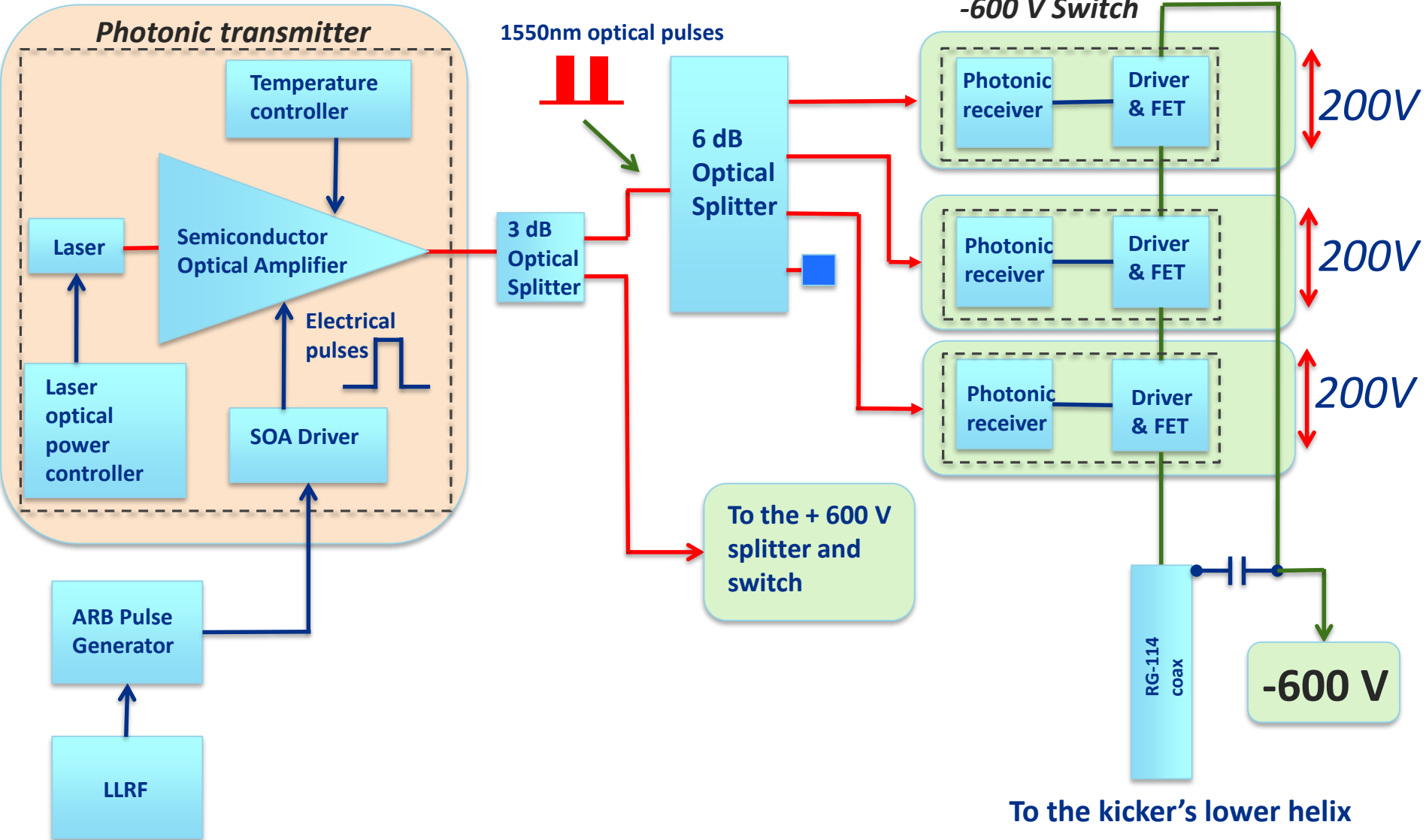
Dispersion compensation:
capacitive plates



Strip line Construction

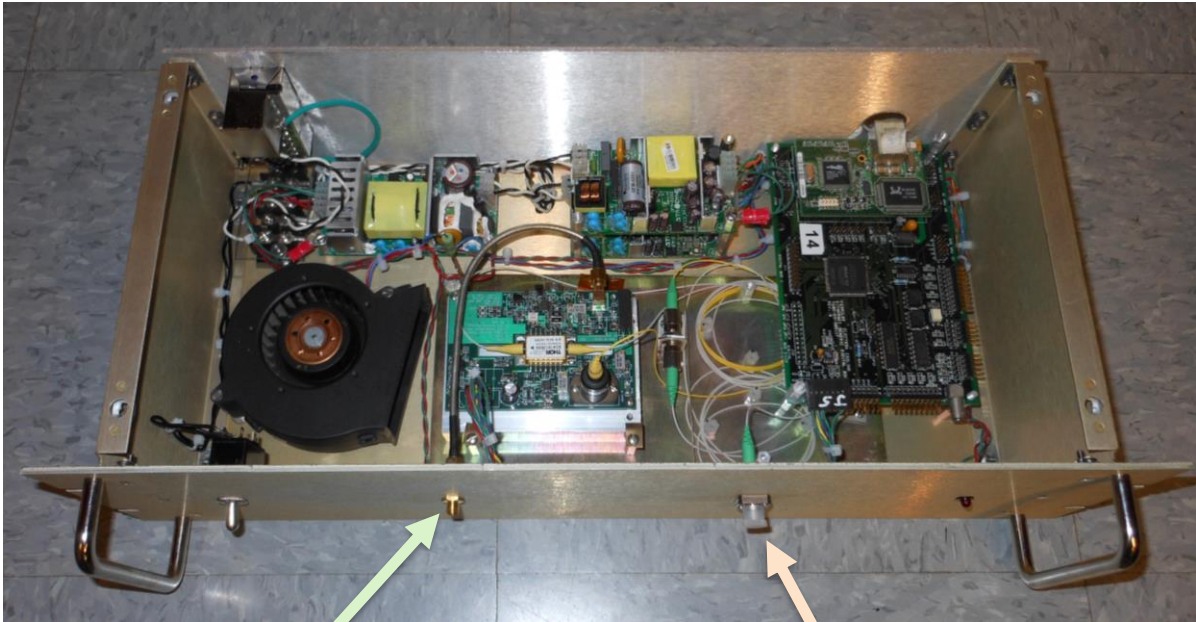


Electric to Fiber Transmitter & Switch



Photonic Transmitter Chassis

Photonic transmitter:

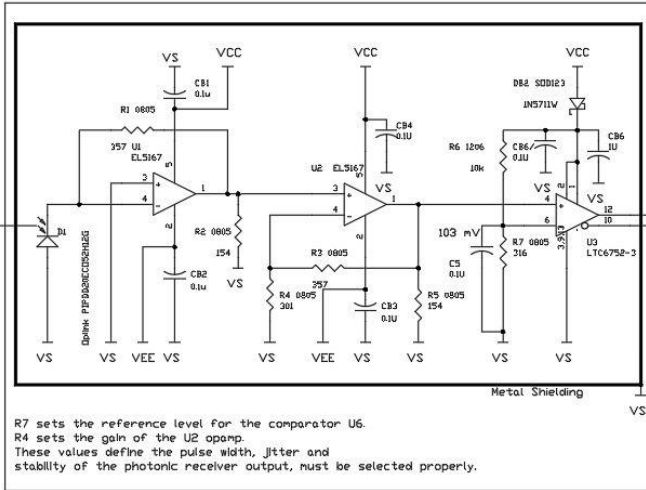


0.6 V TRIGGER INPUT

1550 nm OUTPUT

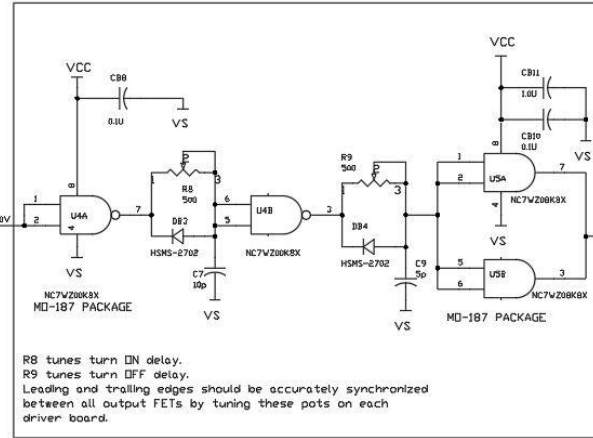
GaNFET Driver Circuit

Detector Stage



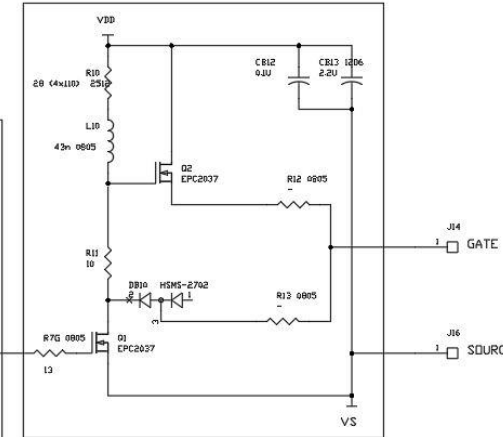
- Photo detector
- 1 GHz opamps: gain (x2)
- 280 MHz comparator

Delay Tuning Stage



Turn-on &
Turn-off
delay adjustment

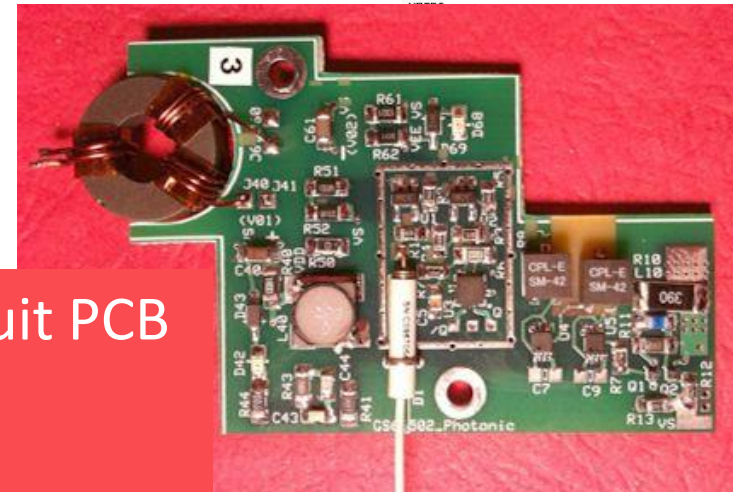
GaNFET Gate Driver



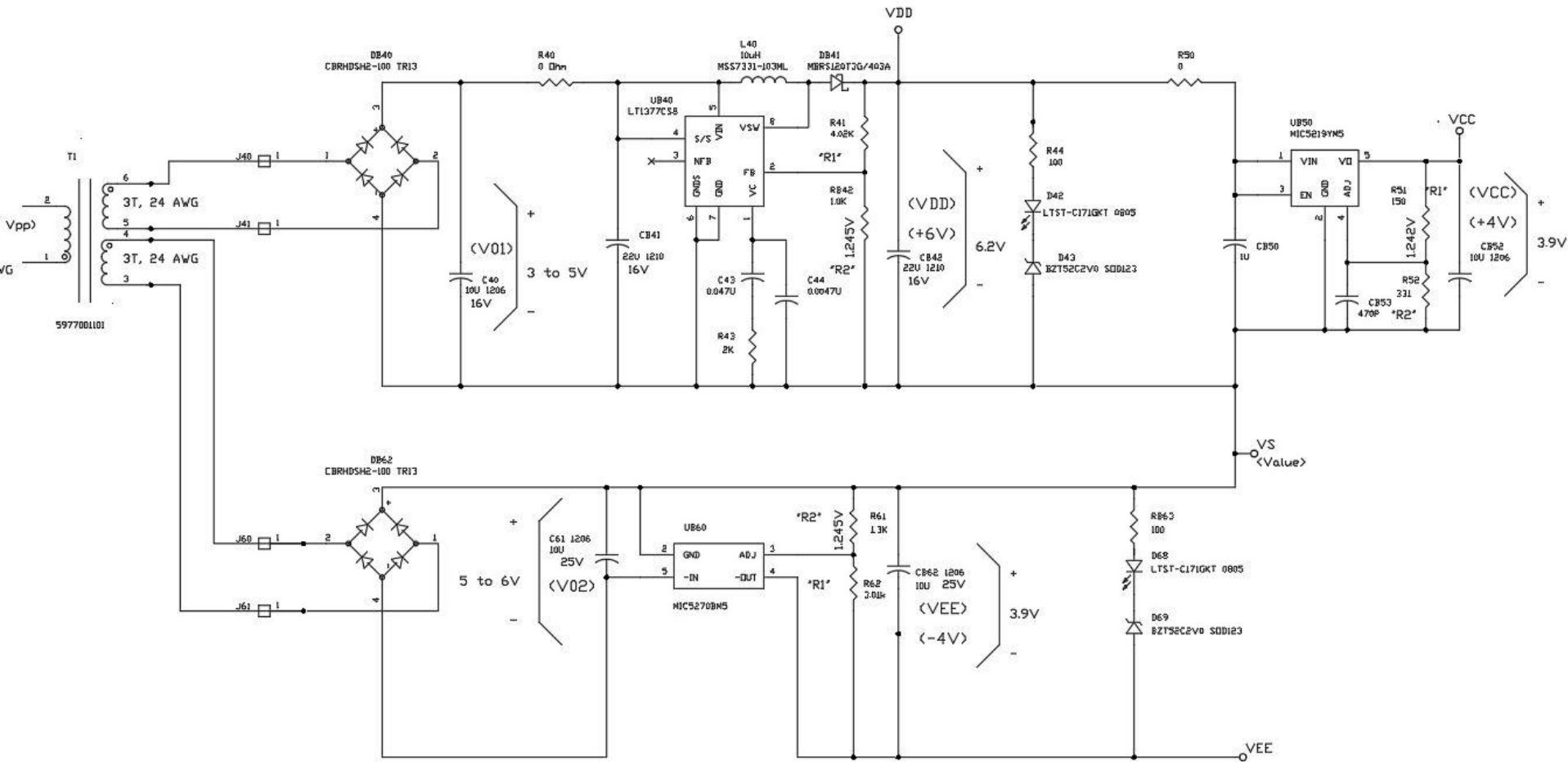
Common source +
source-follower circuit

GaNFET Driver Circuit PCB

- Shields not installed
- size: 2.5" x 1.75"



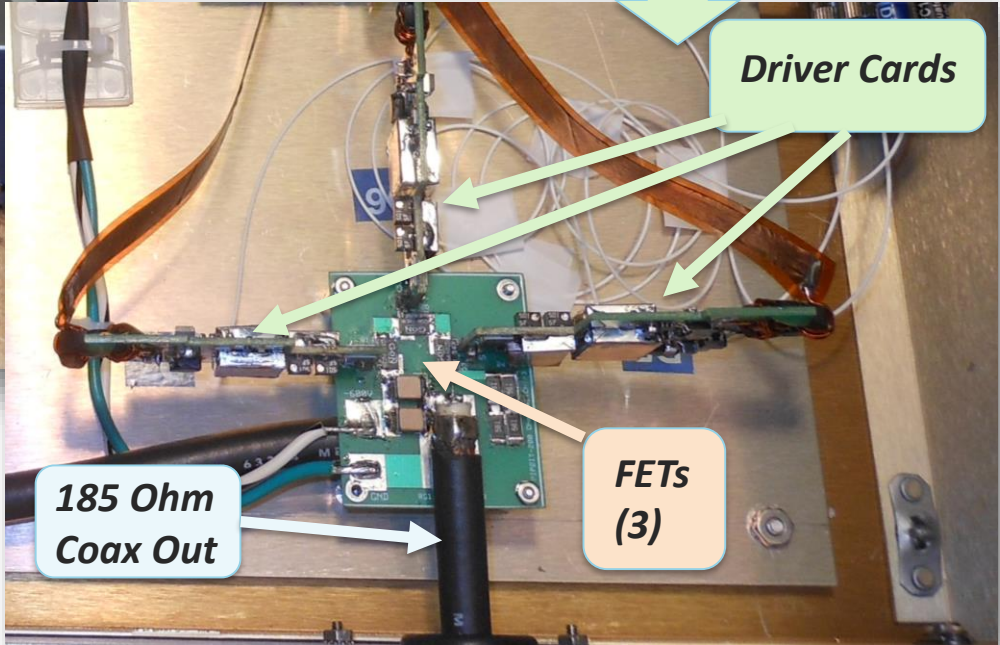
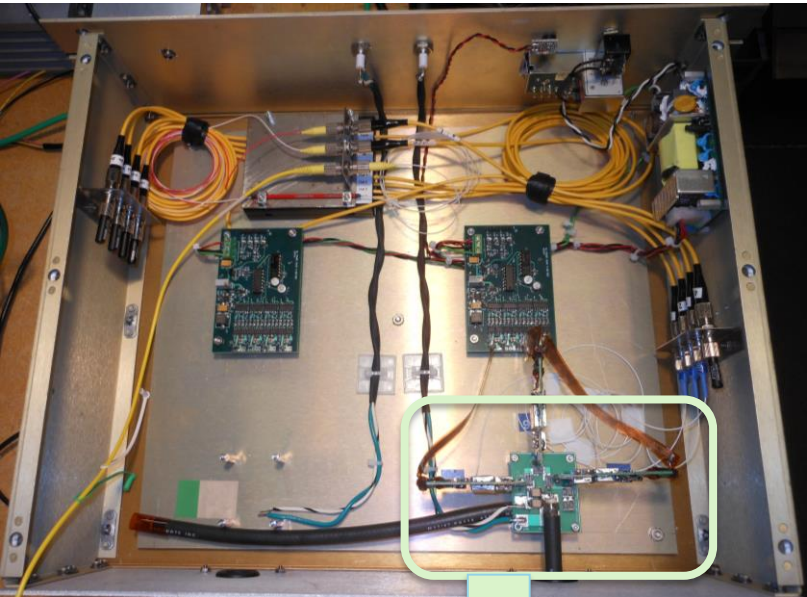
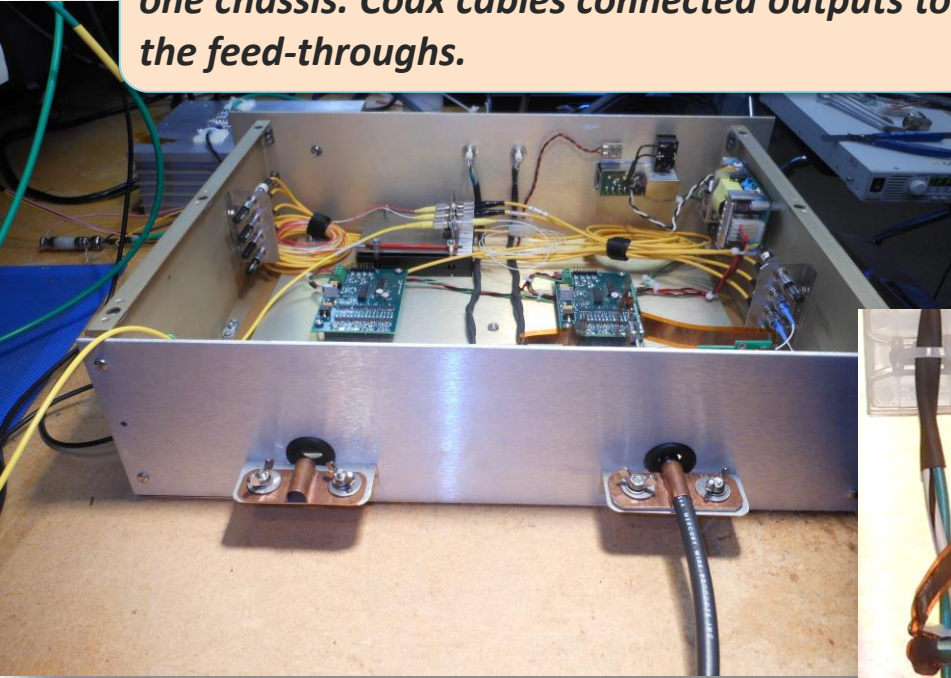
GaNFET Driver Circuit: AC/DC Power



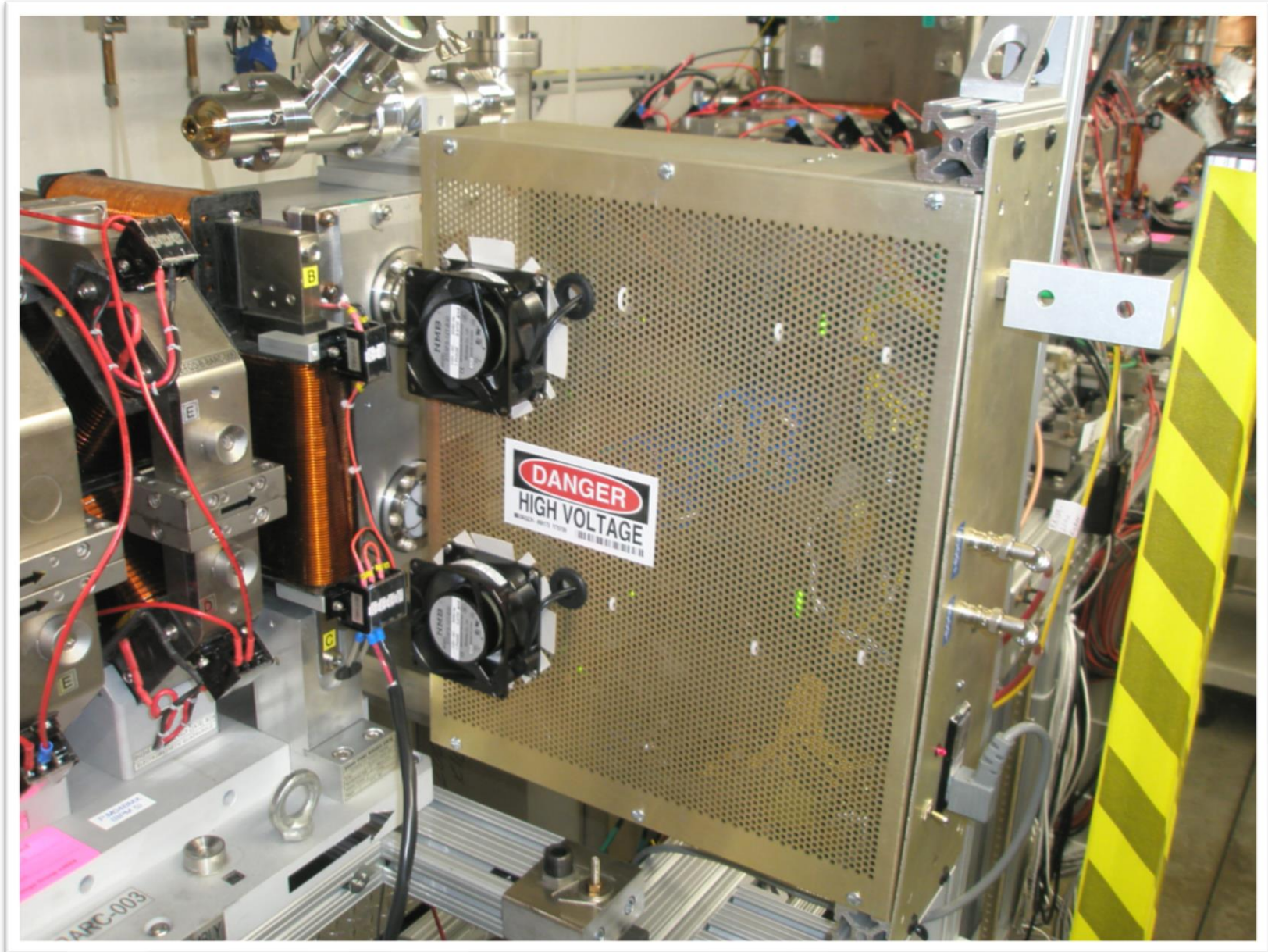
- 3.5 V, 500 kHz AC in
- 3 Well-regulated DC voltages out

The Switch-Driver Chassis (Photonic Gate Version)

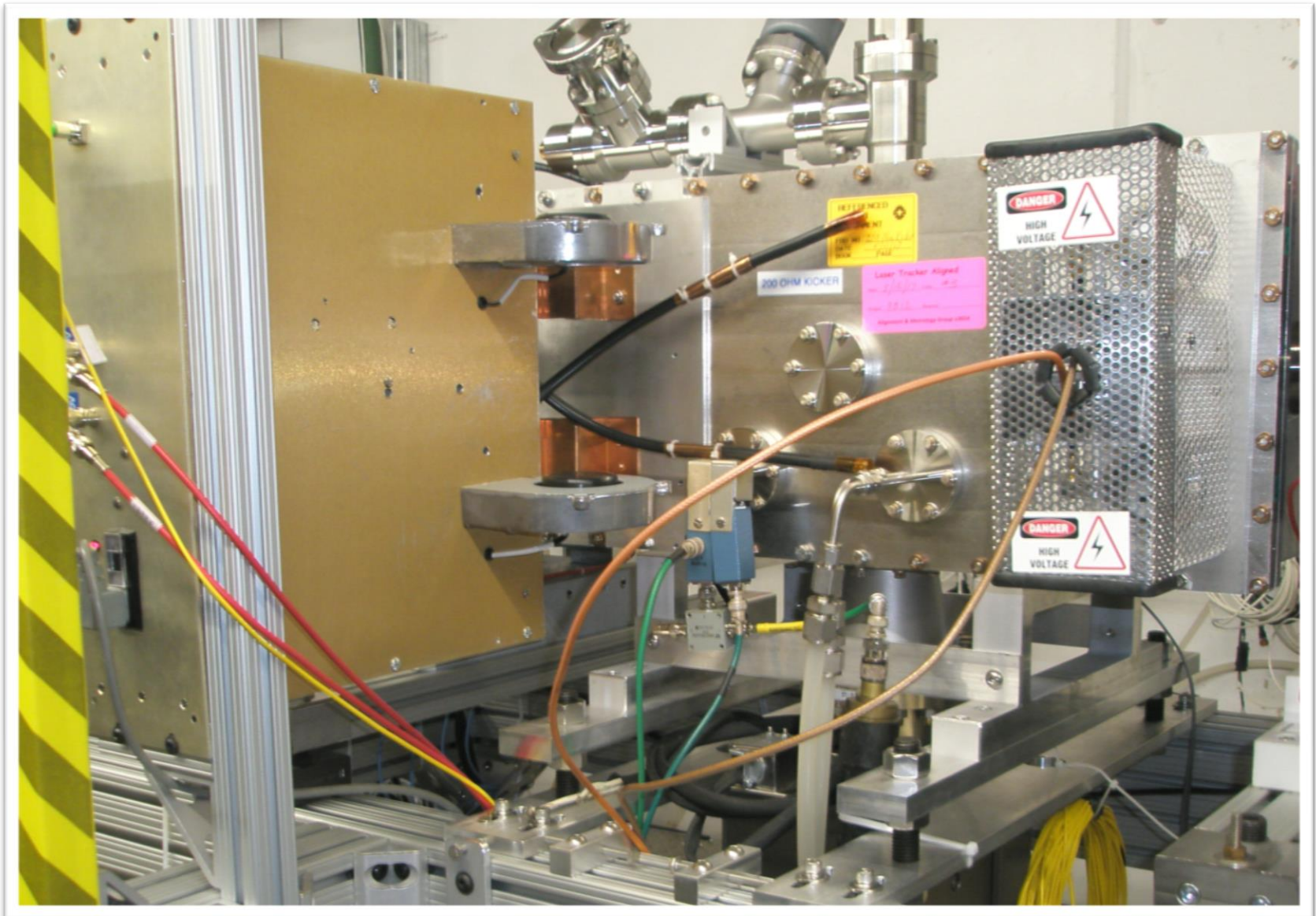
This Version has two switches +/- 600 Volts, in one chassis. Coax cables connected outputs to the feed-throughs.



Driver as installed now in the MEBT



Driver as installed now in the MEBT



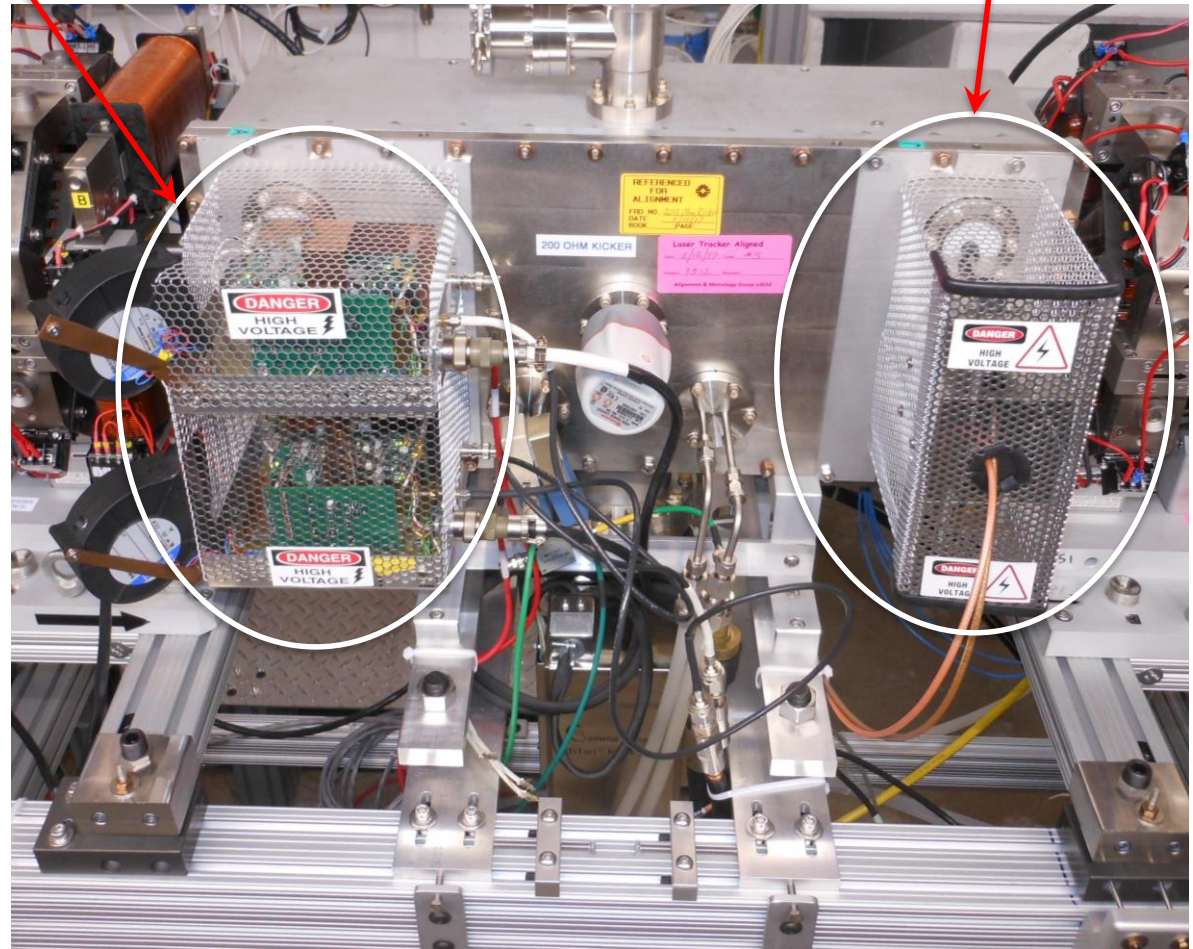
First 200 Ohm Chopper Installed at PIP2-IT (Transformer Gate Version)

Drivers

185 Ω Loads

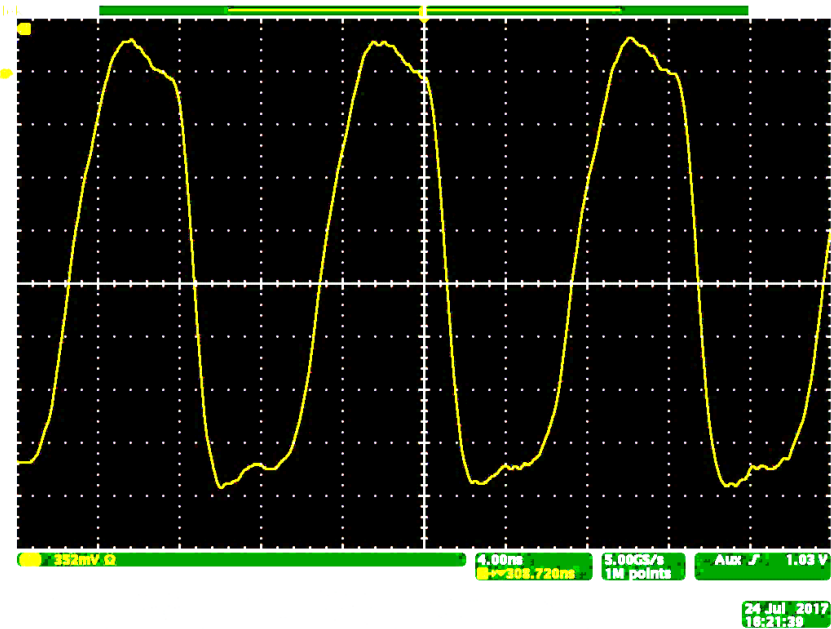
Assembly shown similar to intended final version

- Switch Driver assembly bolted to the helix plate

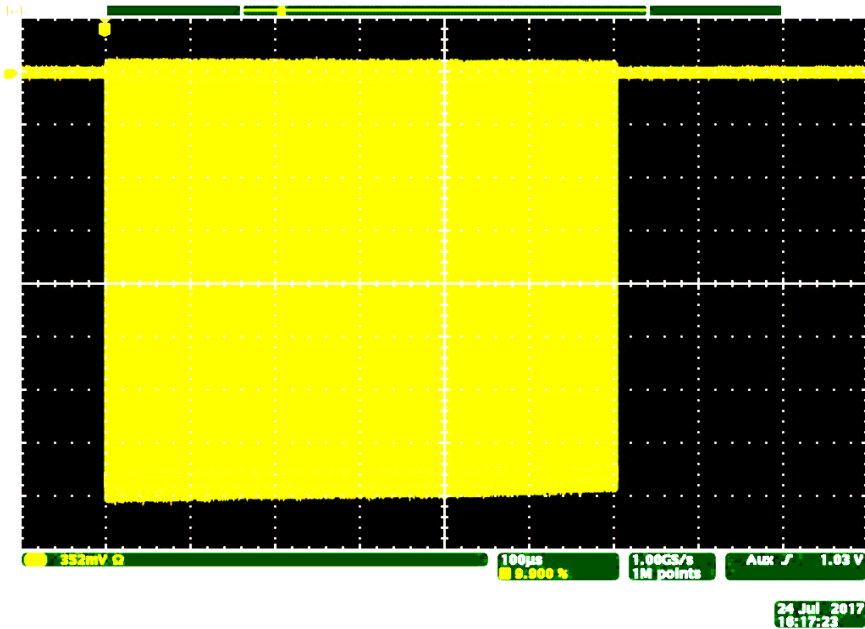


Switch performance

Switching at 81 MHz, 10 us bursts:
600 Vp-p, 4 ns / div



Switching at 45 MHz average rate
for 600 us:
600 Vp-p, 100 us / div

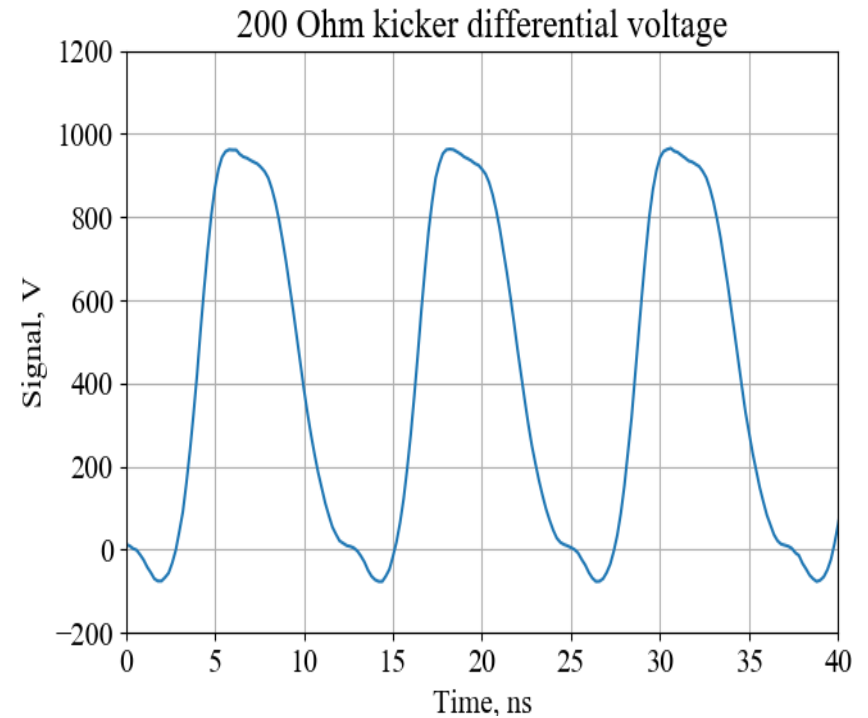
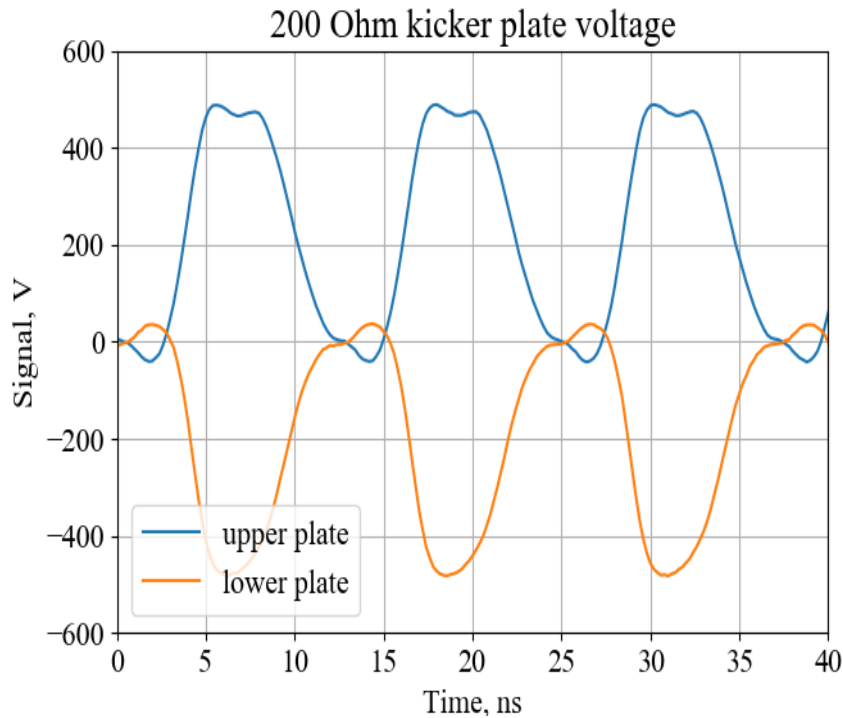


$\pm 500\text{V}$ Bias at 81.25 MHz, 20 Hz Repetition Rate

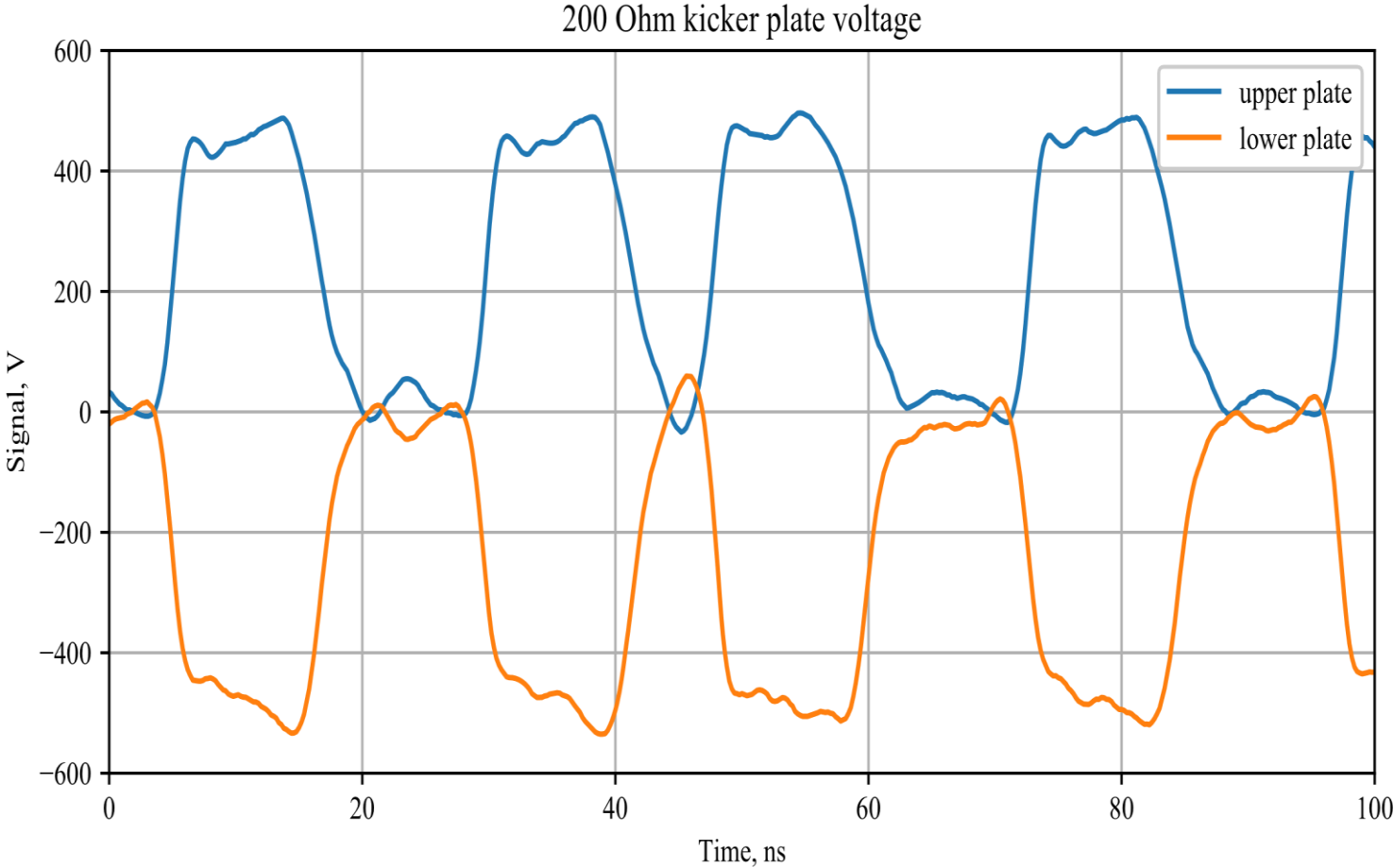
Photonics triggered driver version as operated at PIP2-IT

Individual Helix Waveforms

Differential voltage

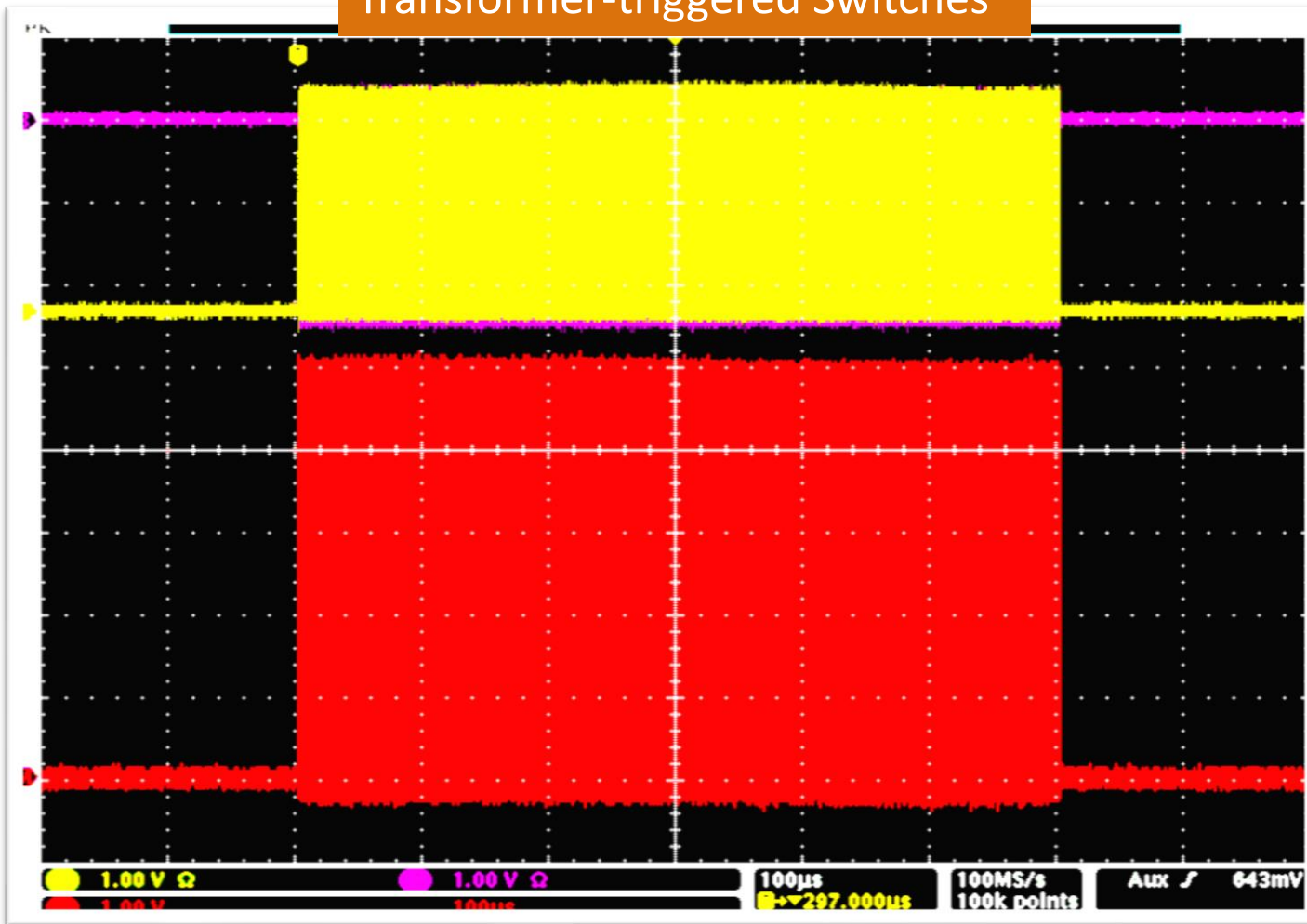


±500V Bias, Arbitrary Pattern



Switching 1100 V, 45 MHz for 600 μ s at 20 Hz

Transformer-triggered Switches



Upper Helix

Lower Helix

Difference
Voltage

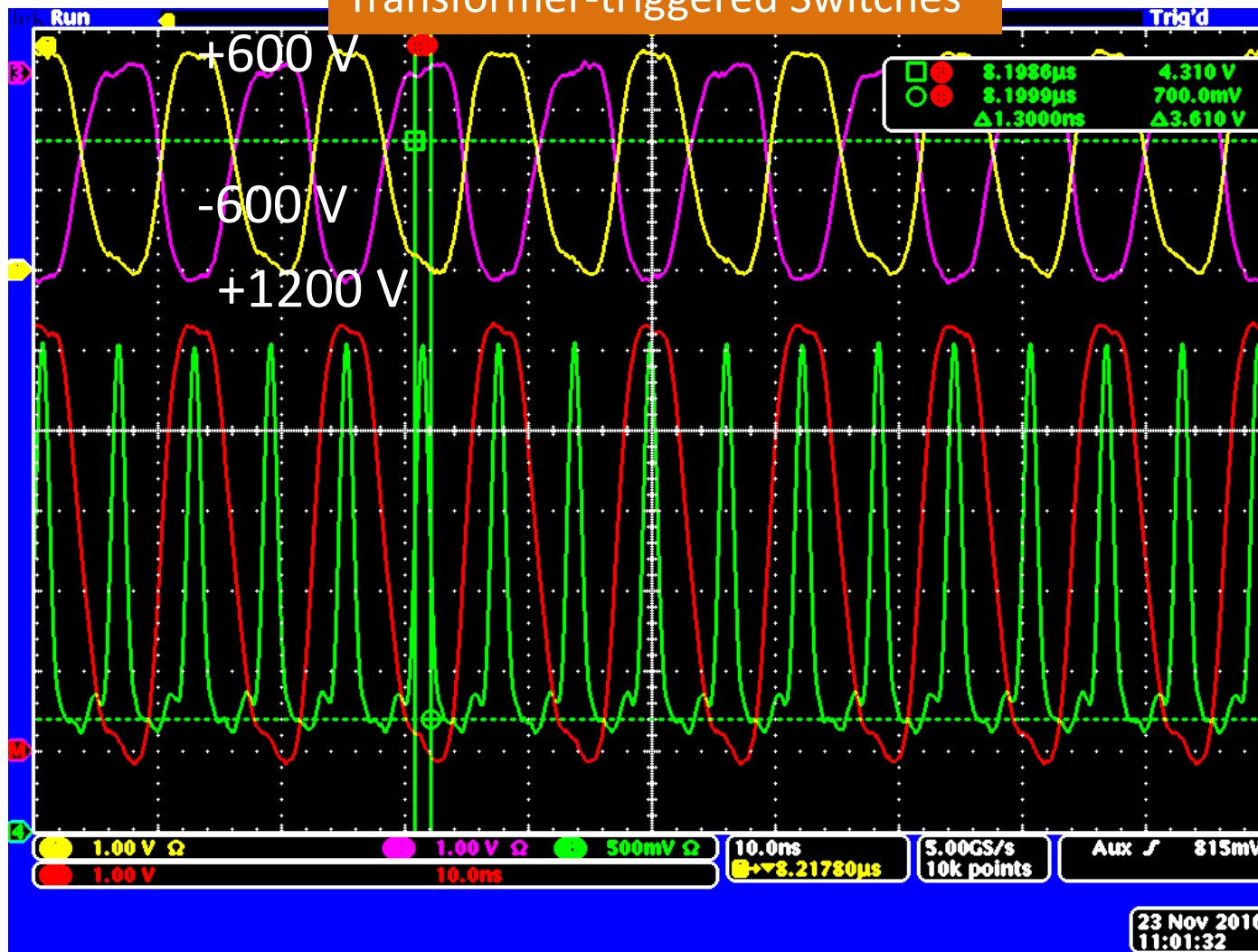
Simulated beam
bunches

Vertical
 ≈ 220 V /div

Horizontal:
100 μ s /div

Switching at 81.25 MHz, ± 600 V; kick every other bunch

Transformer-triggered Switches



Through-voltages

Upper Helix

Lower Helix

Difference
Voltage

Simulated beam
bunches

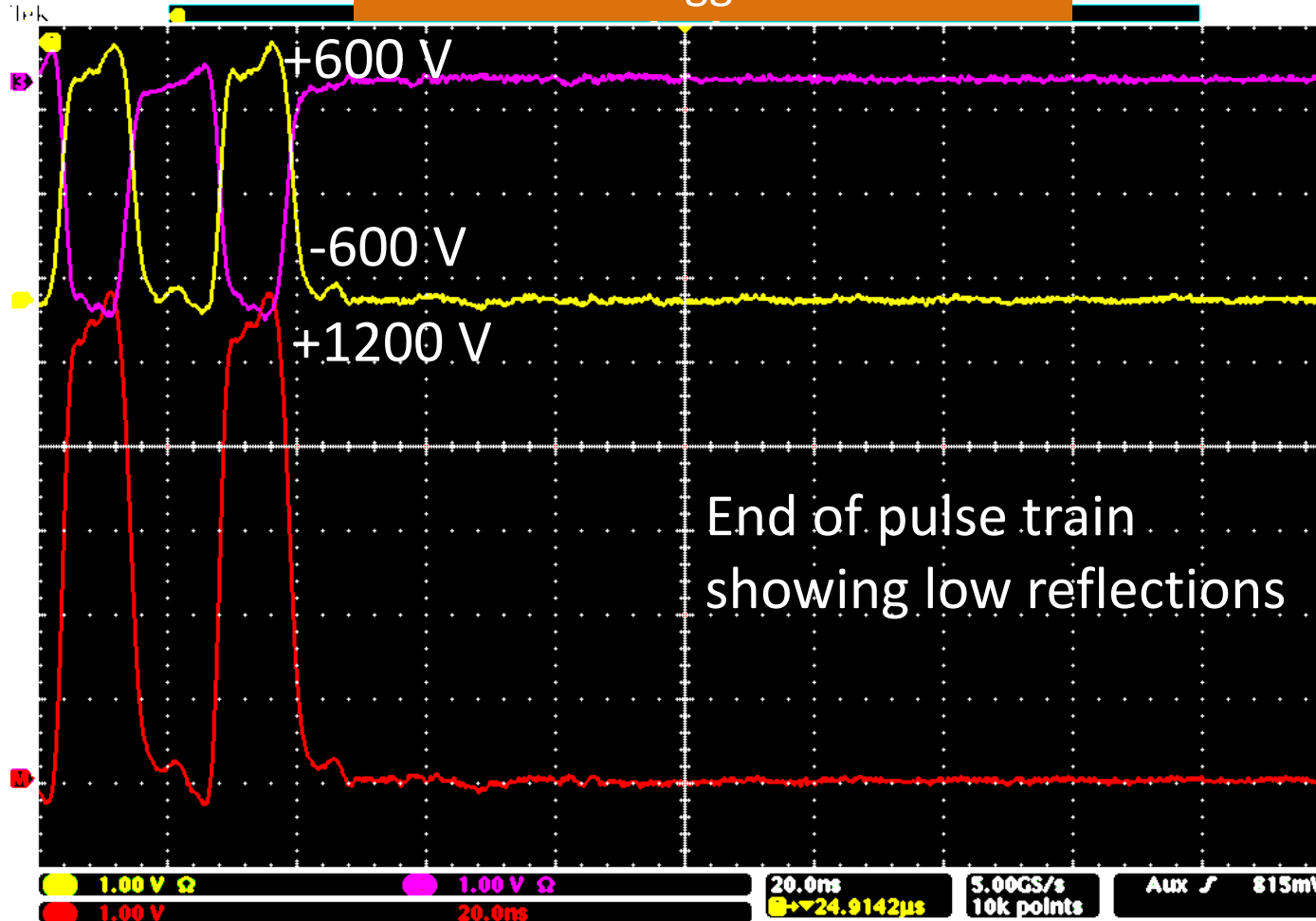
Vertical
 ≈ 220 V /div

Horizontal:
10 ns /div

Amplitudes are consistent up to 40 μ s bursts at 81.25 MHz

Switching at 40.625 MHz, ± 600 V; kick 2 pass 2

Transformer-triggered switches



Through-voltages

Upper Helix

Lower Helix

Difference Voltage

Vertical
 ≈ 220 V /div

Horizontal:
20 ns /div

23 Nov 2016
16:40:07

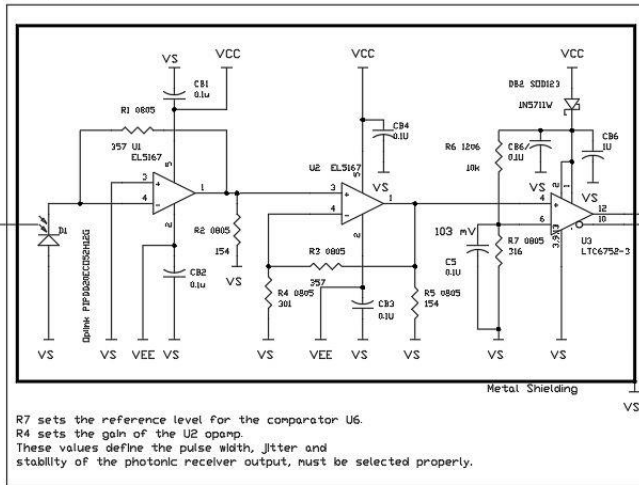
Remaining Design Issues – all straight forward

- Design MEBT Kicker instrumentation interface
- Upgrade GaN FET gate driver stage
- Improve GaNFET PCB layout
 - In-line not in a loop
- Mount switch driver circuits against the feed-throughs
 - No coax
- Design mechanical mounting
 - Drivers
 - Loads
- Address operating voltage limitation
 - Operating voltage now limited to 500 Vdc

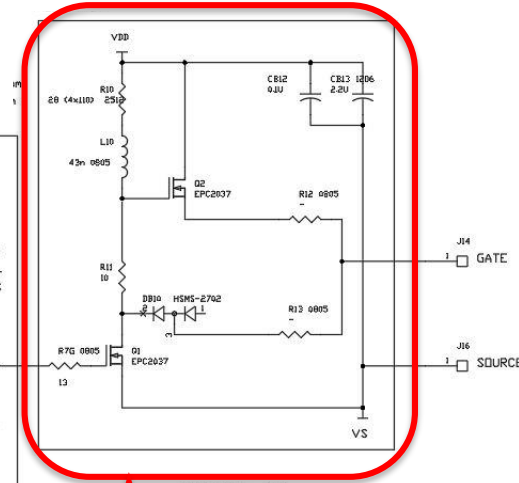
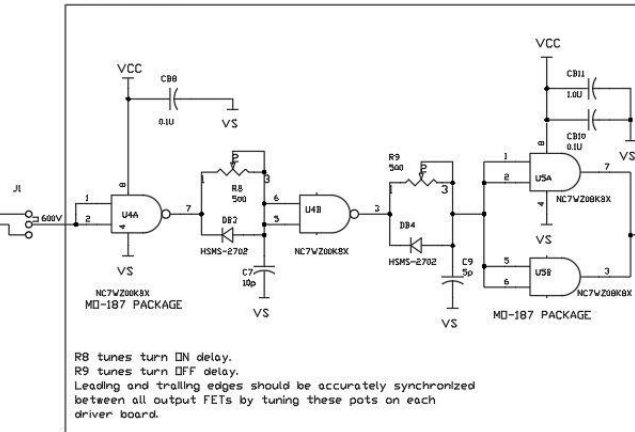
Upgrade GaN FET Driver Stage

GaNFET Gate Drive Stage

Detector Stage

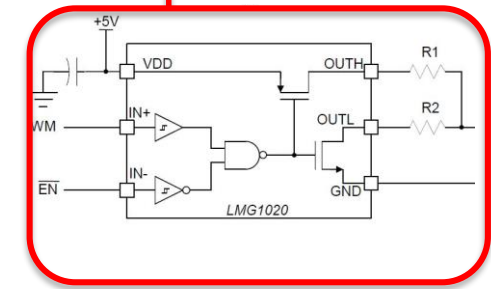


Delay Tuning Stage



LMG1020 GaN FET Gate Driver

- 0.4 ns Trise/fall into 100pF
- 1 ns pulse width
- 7A source, 5A sink currents
- 60 MHz CW rep rate



- Eliminates inductor performance compromise
- Circuit power reduced from 1.25W to 0.1W
 - Forced-air cooling needed to prevent turn-on and -off timing shifts
- Enables reducing PCB size & decrease Driver Circuit parasitics-to-everything

Operating Voltage Limitation

- Problem is an average power dissipation issue
 - Operating voltage envelope sags during the 550 μs
- FET gate threshold voltage is temperature dependent
 - Junction temperatures are not matched
 - FET timing diverges at junction temperatures about 70 $^{\circ}\text{C}$ (absolute)
- Switches do not break;
FETs recover



Cooling enhancement options for >530 V operation

- 5% added to 528 V = 550 V providing desirable margin
- Option 1: build 4-FET switches instead of 3-FET
 - Total switch power dissipation remains roughly the same
 - Per-FET power dissipation would be less
- Option 2: mount GaN FETs on AlO₂ ceramic substrate
 - Cost estimate is ~\$1800 for 10 substrates
- Option 3: improve cooling on existing G10 PCB
 - Increase air flow rate
 - Added small radiators on PCB bottom side

Summary

- A 200 Ω kicker lowers power dissipation everywhere and made it possible to develop a switch-driver and achieve bunch-by-bunch chopping
 - Even for only Booster delivery with its 550 μs macro bunches, 0.5 MHz average rep rates
 - Current helix design will simply be replicated for two kickers
- Both switch driver versions operated with beam at PIP2-IT demonstrated inherent multi-FET switch capabilities:
 - Switching speed to kick and pass bunch-by-bunch
 - Operation at and above 500 Vdc bias
 - To switch at Booster average 45 MHz switching rate
 - Operation at 81.25 MHz for 10's of microseconds at 20 Hz
- Photonic trigger system proved crucial
 - Allows delivery of the arbitrary waveform for Booster injection
 - Provides fine temporal adjustment of on/off delay as well as pulse width
- 4-month test proved GaN FET reliability despite junction thermal cycling
- There are a number of options to improve cooling and allow operation >530 Vdc bias

Acknowledgements

- Management
 - Sasha Shemyakin, et al.
 - Dan Wolff, Chris Jensen
- Engineering contributions
 - Daniil Frolov
 - Alex Chen
 - Howie Pfeffer
 - Mohammed
 - Brian Chase
- Technical assistance
 - Jeff Simmons
 - Kevin Roon
 - Dave Franck
- Vendors
 - GaN Systems, Inc.
 - Gary James, elabinc@mtnhome.com
 - MPF Products, Inc.
 - JFW Industries, Inc.

END

Issues regarding high rep-rate multi-FET switch

- Switching losses at megahertz rates dominate FET dissipation
- Solution: transition faster (for example: well below 2 ns rise/fall)
 - Lowers FET dissipation
 - Increases difficulty of setting and maintaining synchronous timing match
- Reality of mismatched FETs
 - FETs originally timed close (+/- 100ps)
 - Tuned for ~2 ns turn-on time (5-95%)
 - They will be sharing to a significant degree even if we can measure differences in temp.
 - GaN FET rating is 650V
 - They won't break even if grossly mismatched (we've demonstrated this)
 - Mismatch problem is timing shift not thermal melt-down
 - Timing shifts occur at ~70°C junction
 - How many FETs in series to use?
 - 1 FET or 2 FETs not enough
 - 3 or 4 both work
- Real issue is to provide enough substrate cooling for average power

Switch turn-on/-off time difference without output compensation

Turn-on = 2.72 ns

Turn-off = 6.58 ns

